

Title (en)

METHOD FOR CONTACTING AN ELECTRICAL COMPONENT WITH A SUBSTRATE COMPRISING A CONDUCTING STRUCTURE

Title (de)

VERFAHREN ZUR KONTAKTIERUNG EINES ELEKTRISCHEN BAUELEMENTES MIT EINEM EINE LEITERSTRUKTUR AUFWEISENDEN SUBSTRAT

Title (fr)

PROCEDE PERMETTANT D'ETABLIR LE CONTACT ENTRE UN COMPOSANT ELECTRIQUE ET UN SUBSTRAT POSSEDANT UNE STRUCTURE CONDUCTRICE

Publication

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Application

EP 02729854 A 20020405

Priority

- DE 0201254 W 20020405
- DE 10124770 A 20010521

Abstract (en)

[origin: DE10124770C1] Process for contacting an electrical component (2), especially a semiconductor component, to a substrate (1) having a conducting structure (3) comprises applying a connecting unit having a melting point at which the substrate is not damaged between the electrical component and the conducting structure; and melting the connecting unit and solidifying to form a permanent electrically conducting connection. The joining temperature is raised above the glass transition temperature of the substrate so that the substrate plastically deforms with exertion of a pressure on the electrical component and the electrical component is pressed together with the conducting structure into the substrate. Preferred Features: The conducting structure has conductor lines (3) and a contact site. The connecting unit is arranged between a contact of the electrical component and a contact site of the conductor lines.

IPC 1-7

H01L 21/60

IPC 8 full level

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Citation (search report)

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